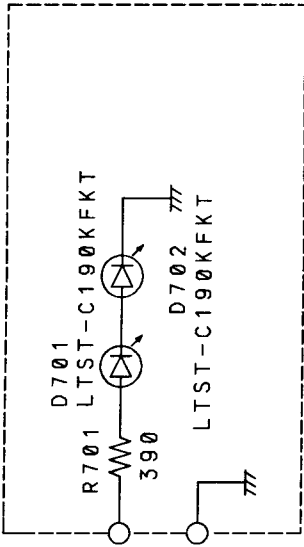
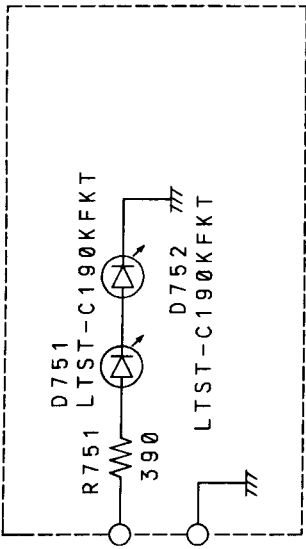


B701 PA-0443



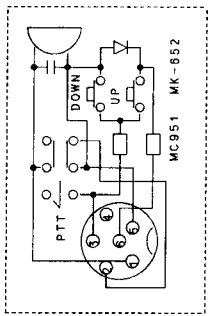
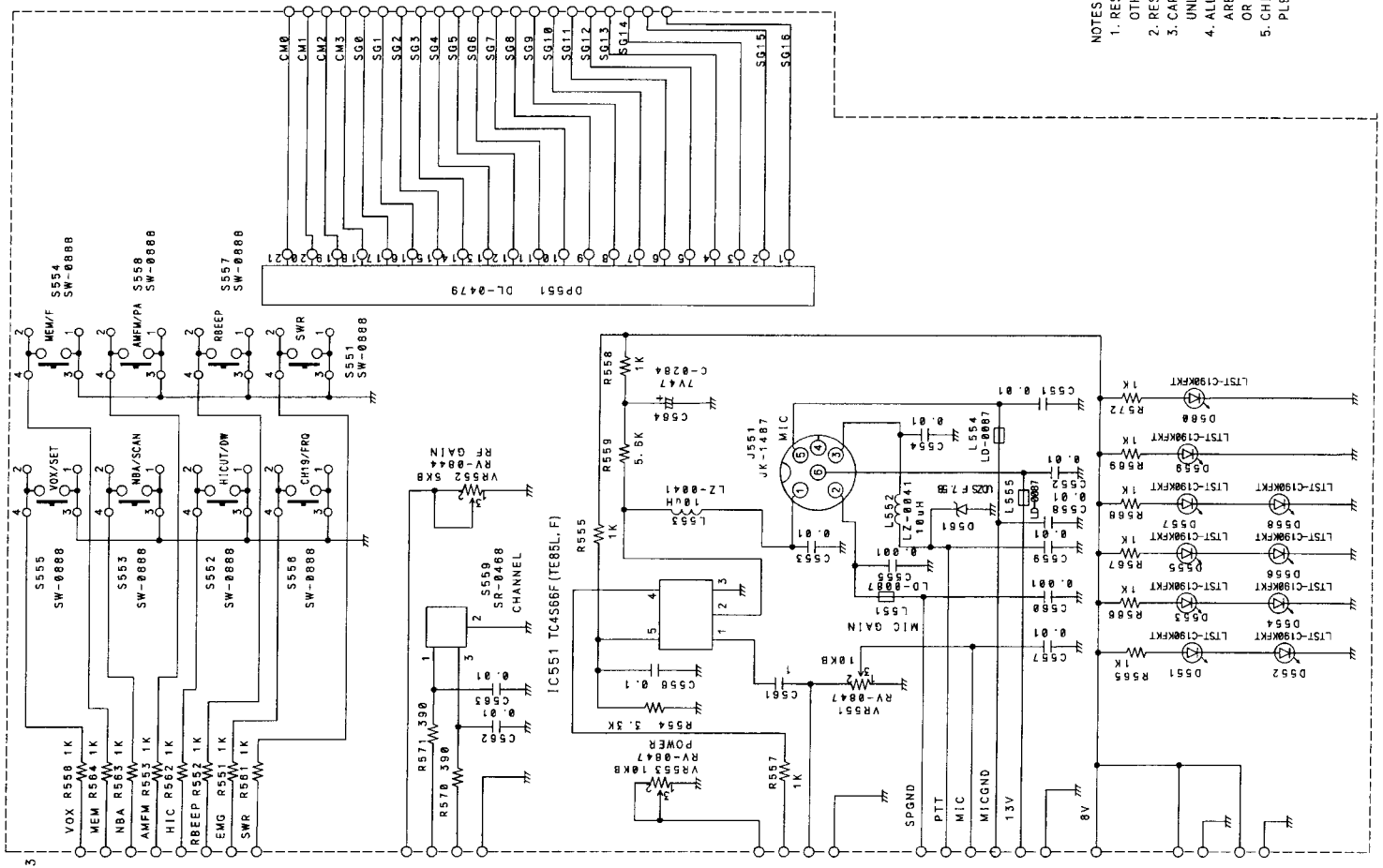
DESIGN	DRAWN. BY	UNIDEN No.	MODEL No.
08/06/27	08/06/27	UT376ZH	JFKII ASC
HOKA	HOKA	TITLE LED R PCB	
CHECK. BY	APPRO. BY	SCHEMATIC DIAGRAM	
08/06/27	08/06/27	DRAWING No.	
MATSU	NABE		
REV. No			UNIDEN CORP.

B750 PA-0443



DESIGN	DRAWN. BY	UNIDEN No.	MODEL No.
08/06/27	08/06/27	UT376ZH	JFKI ASC
HOKA	HOKA	TITLE LED L PCB	
CHECK. BY	APPRO. BY	SCHEMATIC DIAGRAM	
08/06/27	08/06/27	DRAWING No.	
MATSU	NABE		
REV. No			UNIDEN CORP.

B551  
PA-0443

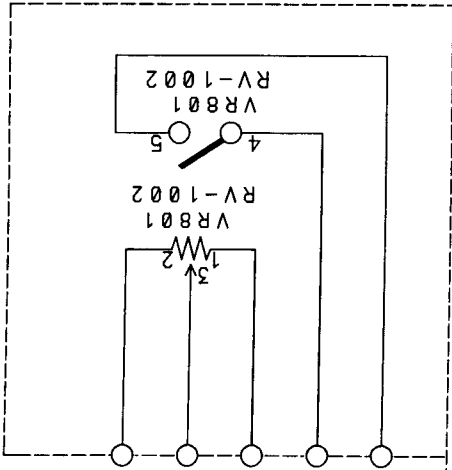


- NOTES:
1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K=KILO OHM, M=MEG OHM)
  2. RESISTOR WATTAGES ARE [1/10W] UNLESS OTHERWISE NOTED.
  3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED. (P=PICTO-MICRO FARAD)
  4. ALL CAPACITORS TEMPERATURE CHARACTERISTICS ARE [CH] (LESS THAN 820PF) OR [B] (MORE THAN 1000PF) UNLESS OTHERWISE NOTED.
  5. CHIP PARTS ARE NOT SPECIFIED IN THIS DRAWING. PLEASE REFER TO THE PARTS LIST FOR THE CHIP PARTS.

DESIGN	UNIDEN No.	MODEL No.
HOKA	UT376ZH	JFK II ASC
2008.06.27	TITLE	FRONT PCB
CHECK BY	APPROV. BY	SCHEMATIC DIAGRAM
MATSU	NABE	DRAWING No.
2008.06.27	2008.06.27	
REV. No		UNIDEN CORP.

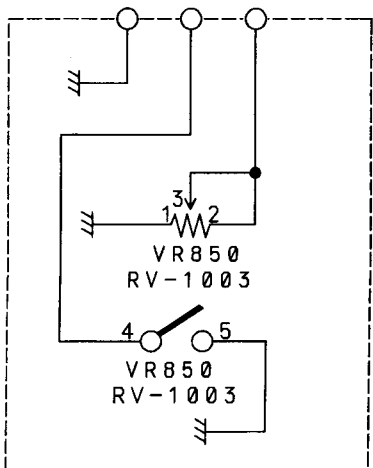
B801

PA-0443



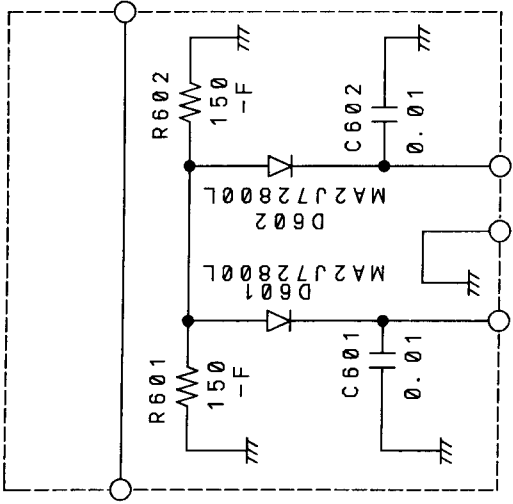
DESIGN	DRAWN. BY	UNIDEN No.	MODEL No.
08/06/27	08/06/27	UT376ZH	JFKII ASC
HOKA	HOKA	TITLE VOL PCB	
CHECK. BY	APPRO. BY	SCHEMATIC DIAGRAM	
08/06/27	08/06/27	DRAWING No.	
MATSU	NABE		
REV. No			UNIDEN CORP.

B 8 5 0 PA-0443



DESIGN	DRAWN. BY	UNIDEN No.	MODEL No.
08/06/27	08/06/27	UT376ZH	JFKII ASC
HOKA	HOKA	TITLE	SO PCB
CHECK. BY	APPRO. BY	SCHEMATIC DIAGRAM	
08/06/27	08/06/27	DRAWING No.	
MATSU	NABE		
REV. No		UNIDEN CORP.	

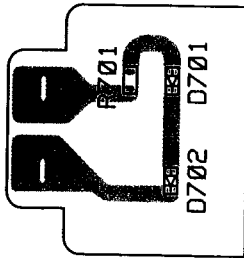
B601 PA-0444



DESIGN	DRAWN. BY	UNIDEN No.	MODEL No.
08/06/27	08/06/27	UT376ZH	JFKI ASC
HOKA	HOKA	TITLE	SWR PCB
CHECK. BY	APPRO. BY	SCHEMATIC DIAGRAM	
08/06/27	08/06/27	DRAWING No.	
MATSU	NABE		
REV. No		UNIDEN CORP.	

Use Pb Free Solder

B701 PA-443AA 2/5(TOP VIEW)



D701	LTST-C190KFKT
D702	LTST-C190KFKT
R701	390 1/16W J

D701~702 POLARITY



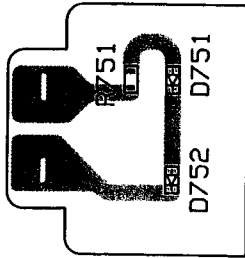
NOTES:

- RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K-KILO OHM. M-MEG OHM)

DESIGN. BY	HOKA	UNIDEN NO.	UT376ZH	MODEL NO.	JFKI ASC
DRAWN. BY	HOKA				
CHECK. BY	08/07/02	APPRO. BY	NABE	TITLE LED R PCB CHIP LAYOUT TOP VIEW	
				DRAWING NO.	
REV. NO.				UNIDEN CORP.	

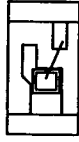
Use Pb Free Solder

B750 PA-443AA 3/5(TOP VIEW)



D751	LTST-C190KFKT
D752	LTST-C190KFKT
R751	390 1/16W J

D751~752 POLARITY



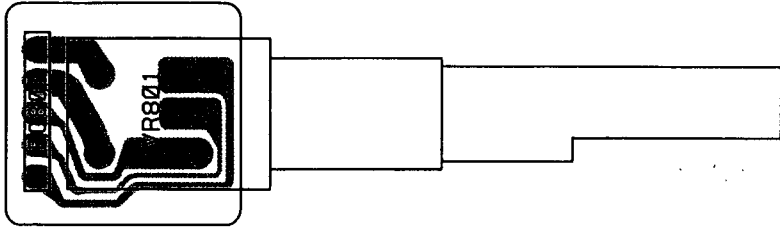
NOTES:

1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K-KILO OHM. M-MEG OHM)

DESIGN. BY	HOKA	UNIDEN NO.	UT376ZH	MODEL NO.	JFKI ASC
DRWN. BY	HOKA				
CHECK. BY	MATSU	DATE	08/07/02	TITLE	LED L PCB
		APPRO. BY	NABE		CHIP LAYOUT TOP VIEW
			08/07/02	DRAWING NO.	
REV. NO.					UNIDEN CORP.



B801 PA-443AA 4/5(TOP VIEW)

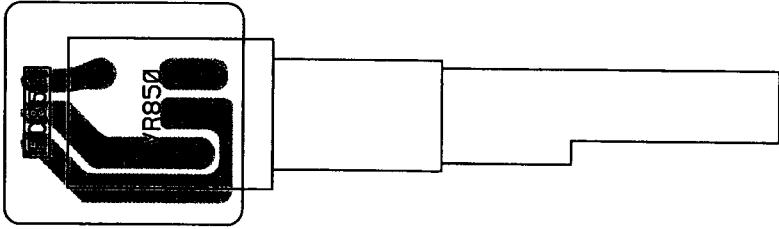


Use Pb Free Solder

FC801	WF-385 3.5-55-3.5 5P
VR801	RV-1002

DESIGN. BY HOKA	DRAWN. BY HOKA	UNIDEN NO. UT376ZH	MODEL NO. JFK II ASC
08/07/02	08/07/02	TITLE VOL PCB	
CHECK. BY MATSU	APPRO. BY NABE	PARTS ASS'Y TOP VIEW	
08/07/02	08/07/02	DRAWING NO.	
REV. NO.			UNIDEN CORP.

B850 PA-443AA 5/5(TOP VIEW)

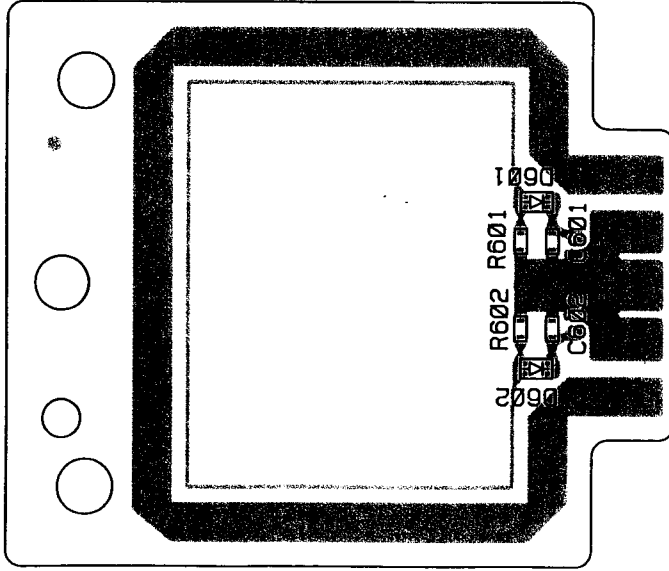


Use Pb Free Solder

FC851	WF-383 3.5-55-3.5 3P
VR850	RV-1003

DESIGN. BY HOKA	DRAWN. BY HOKA	UNIDEN NO. UT376ZH	MODEL NO. JFK II ASC
08/07/02	08/07/02	TITLE SQ PCB	
CHECK. BY MATSU	APPRO. BY NABE	PARTS ASS'Y TOP VIEW	
08/07/02	08/07/02	DRAWING NO.	
REV. NO.			UNIDEN CORP.

# B601 PA-444AA (TOP VIEW)



Use Pb Free Solder

D601	MA2J72800L
D602	MA2J72800L
C601	0.01UF 50V K B
C602	0.01UF 50V K B
R601	150 1/16W F
R602	150 1/16W F

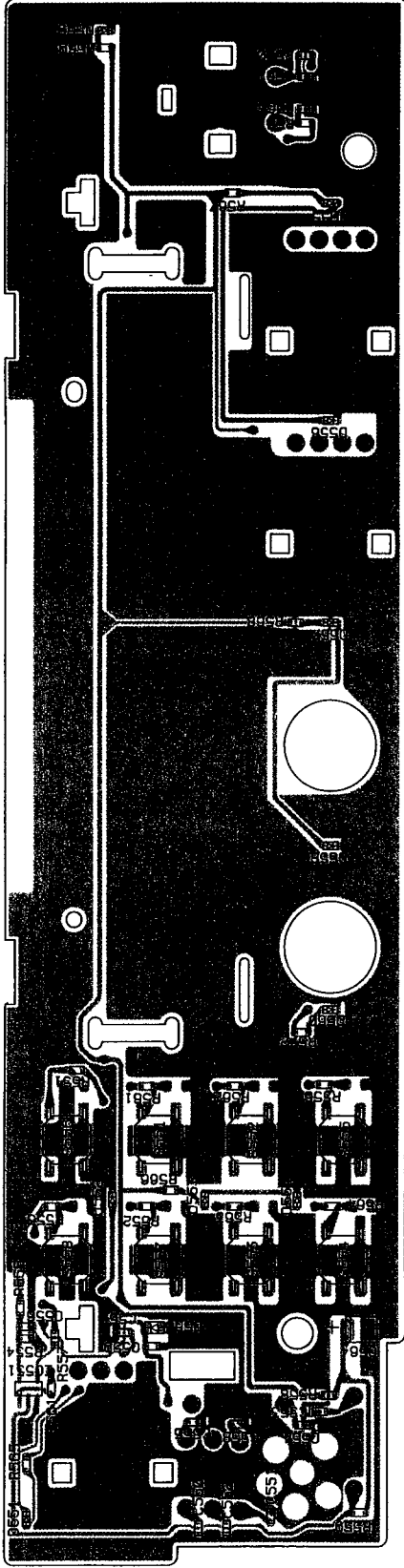
**NOTES:**

1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED.  
(K-KILO OHM, M-MEG OHM)

DESIGN. BY	HOKA	DRAWN. BY	HOKA	UNIDEN NO.	UT376ZH	MODEL NO.	JFK II ASC
CHECK. BY	08/07/02	APPRO. BY	08/07/02	TITLE	SWR PCB	CHIP LAYOUT TOP VIEW	
	MATSU		NABE	DRAWING NO.			
	08/07/02		08/07/02				
REV. NO.					UNIDEN CORP.		

B551 PA-443AA 1/5 (TOP VIEW)

Use Pb Free Solder



C551	0.01	
C552	0.01	
C553	0.01	
C554	0.01	
C555	0.001	
C556	0.1 16V	
C557	0.01	
C558	0.01	
C559	0.01	
C560	0.001	
C561	1 10V	
C562	0.01	
C563	0.01	
C564	47 7V C-284	
D551	LTST-C190KFKT	
D552	LTST-C190KFKT	
D553	LTST-C190KFKT	
D554	LTST-C190KFKT	
D555	LTST-C190KFKT	
D556	LTST-C190KFKT	
D557	LTST-C190KFKT	
D558	LTST-C190KFKT	
D559	LTST-C190KFKT	

D560	LTST-C190KFKT	
D561	UDZSF 7.5B TE-17	
IC551	TC4S66F(TE85L,F)	
R551	1K	
R552	1K	
R553	1K	
R554	3.3K	
R555	1K	
R556	1K	
R557	1K	
R558	1K	
R559	5.6K	
R561	1K	
R562	1K	
R563	1K	
R564	1K	
R565	1K	
R566	1K	
R567	1K	
R568	1K	
R569	1.5K	

R570	390	
R571	390	
R572	3.3K	
S551	SW-888 RS-187R05A2-DS MT	
S552	SW-888 RS-187R05A2-DS MT	
S553	SW-888 RS-187R05A2-DS MT	
S554	SW-888 RS-187R05A2-DS MT	
S555	SW-888 RS-187R05A2-DS MT	
S556	SW-888 RS-187R05A2-DS MT	
S557	SW-888 RS-187R05A2-DS MT	
S558	SW-888 RS-187R05A2-DS MT	

D551-561 POLARITY



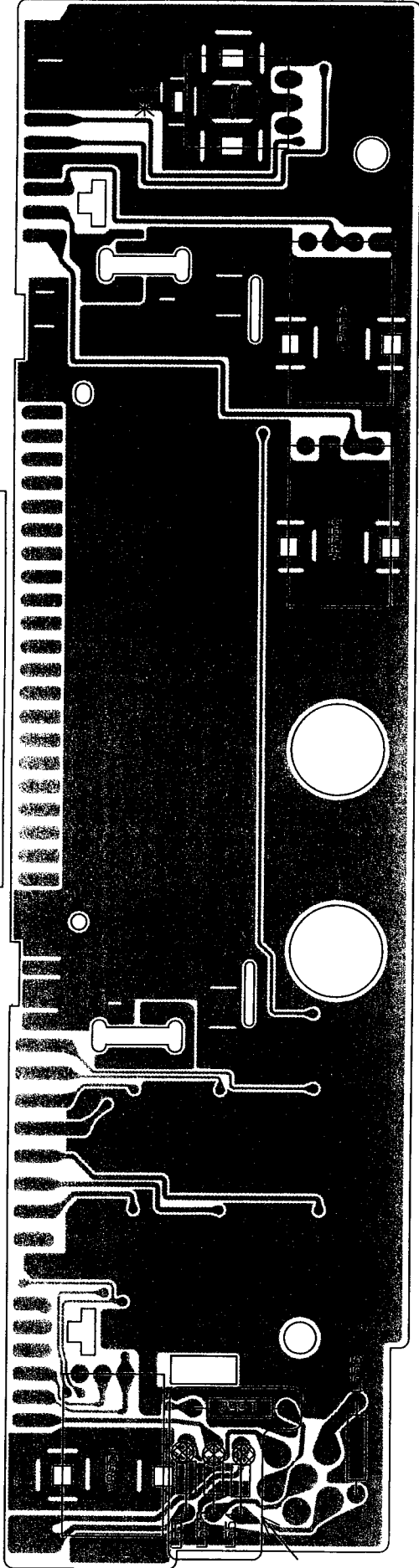
NOTES:

1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K=KILLO OHM, M=MEG OHM)
2. RESISTOR TOLERANCES ARE 1/16W UNLESS OTHERWISE NOTED.
3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED. (P=PICTO-MICRO FARAD)
4. ALL CAPACITORS ARE 50V & SIZE ARE 1608 UNLESS OTHERWISE NOTED.
5. ALL CAPACITORS TEMPERATURE CHARACTERISTICS ARE CH (LESS THAN 820PF) OR B (MORE THAN 1000PF) UNLESS OTHERWISE NOTED.

DESIGN BY	UNIDEN NO.	MODEL NO.
HOKA	UTS76ZH	JFK I ASC
DATE	TITLE	
8/87/82	FRONT ASS'Y	
CHECK BY	APP'D BY	CHIP LAYOUT TOP VIEW
MATSU	NABE	
DATE	DATE	
8/87/82	8/87/82	
REV. NO.	UNIDEN CORP.	

B551 PA-443AA 1/5 (TOP VIEW)

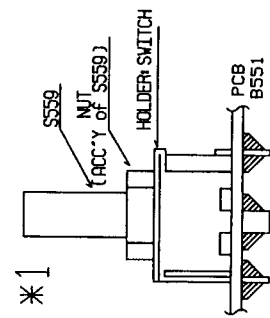
Use Pb Free Solder



\*2

\*2  
ALL PARTS INSIDE  
THIS AREA  
MUST BE FLAT MOUNT

● : YELLOW BOND LOCK (SC-121)  
(ZABD7001005)



\*1

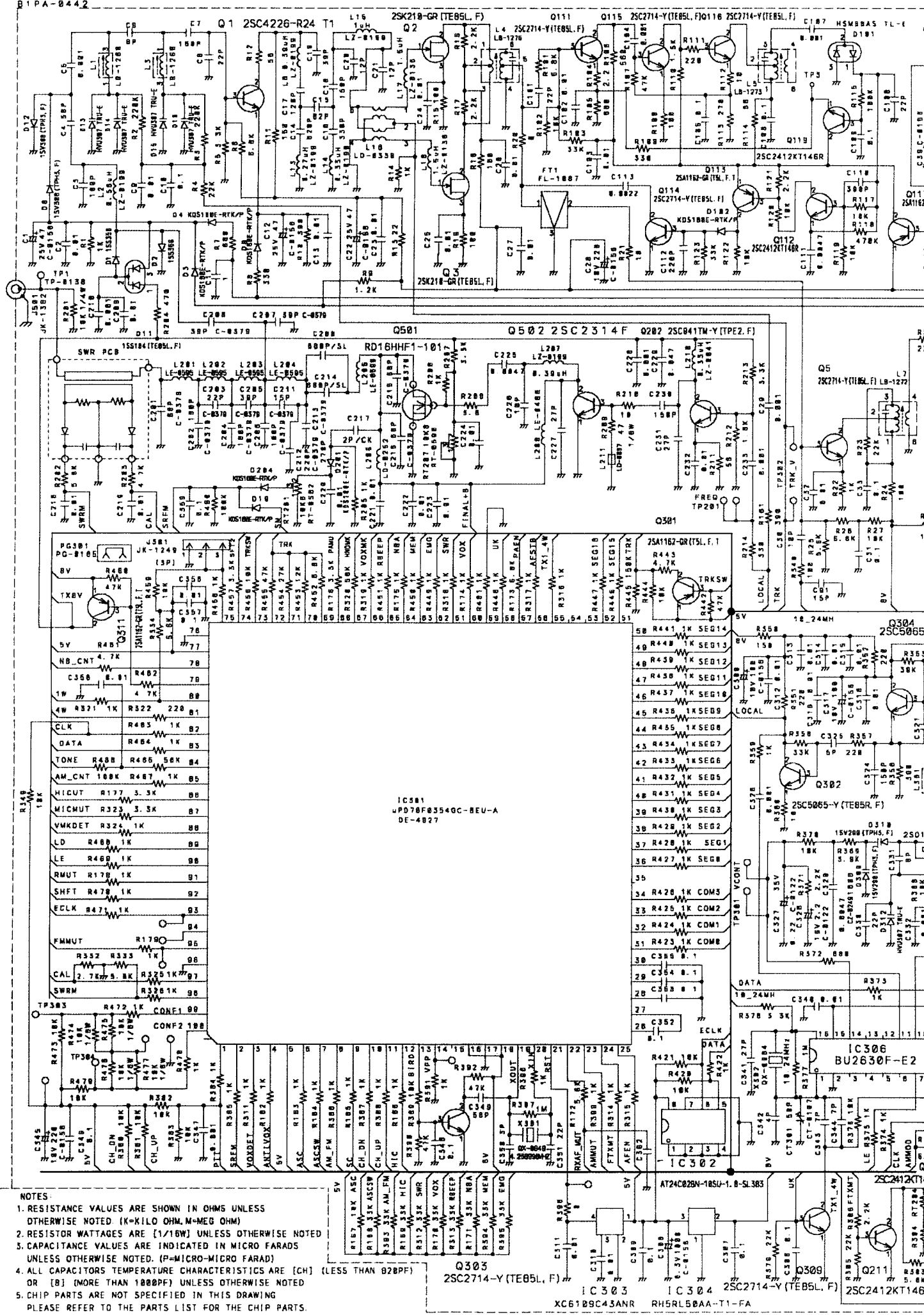
L551	LD-087	L5RH3X5X1
L552	LZ-041	10UH K
L553	LZ-041	10UH K
L554	LD-087	L5RH3X5X1
L555	LD-087	L5RH3X5X1
S559	SR-468	
VR551	RV-847	RK11K1140 10KB
VR552	RV-844	RK11K1140 5KB
VR553	RV-847	RK11K1140 10KB

DESIGN BY	HOKA	DRAWN BY	HOKA	UNIDEN NO.	UT576ZH	MODEL NO.	JFK I ASC
CHECK BY	MATSU	APPRO. BY	NABE	TITLE	FRONT ASS'Y		
REV.	08/07/02	REV.	08/07/02	PARTS ASS'Y TOP VIEW			
		DRAWING NO.					
REV. NO.					UNIDEN CORP.		

1A

1B

B1 PA-0442



- NOTES:
1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED (K=KILO OHM, M=MEG OHM)
  2. RESISTOR WATTAGES ARE [1/16W] UNLESS OTHERWISE NOTED
  3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED. (P=MICRO-MICRO FARAD)
  4. ALL CAPACITORS TEMPERATURE CHARACTERISTICS ARE [CH] OR [B] (MORE THAN 100PPF) UNLESS OTHERWISE NOTED
  5. CHIP PARTS ARE NOT SPECIFIED IN THIS DRAWING PLEASE REFER TO THE PARTS LIST FOR THE CHIP PARTS.

IC301  
P078F83540C-BEU-A  
DE-4827

IC302  
AT24C25N-1RSU-1.0-SL383

Q303  
2SC2714-Y (TE85L, F)

IC303

IC304

2SC2714-Y (TE85L, F)

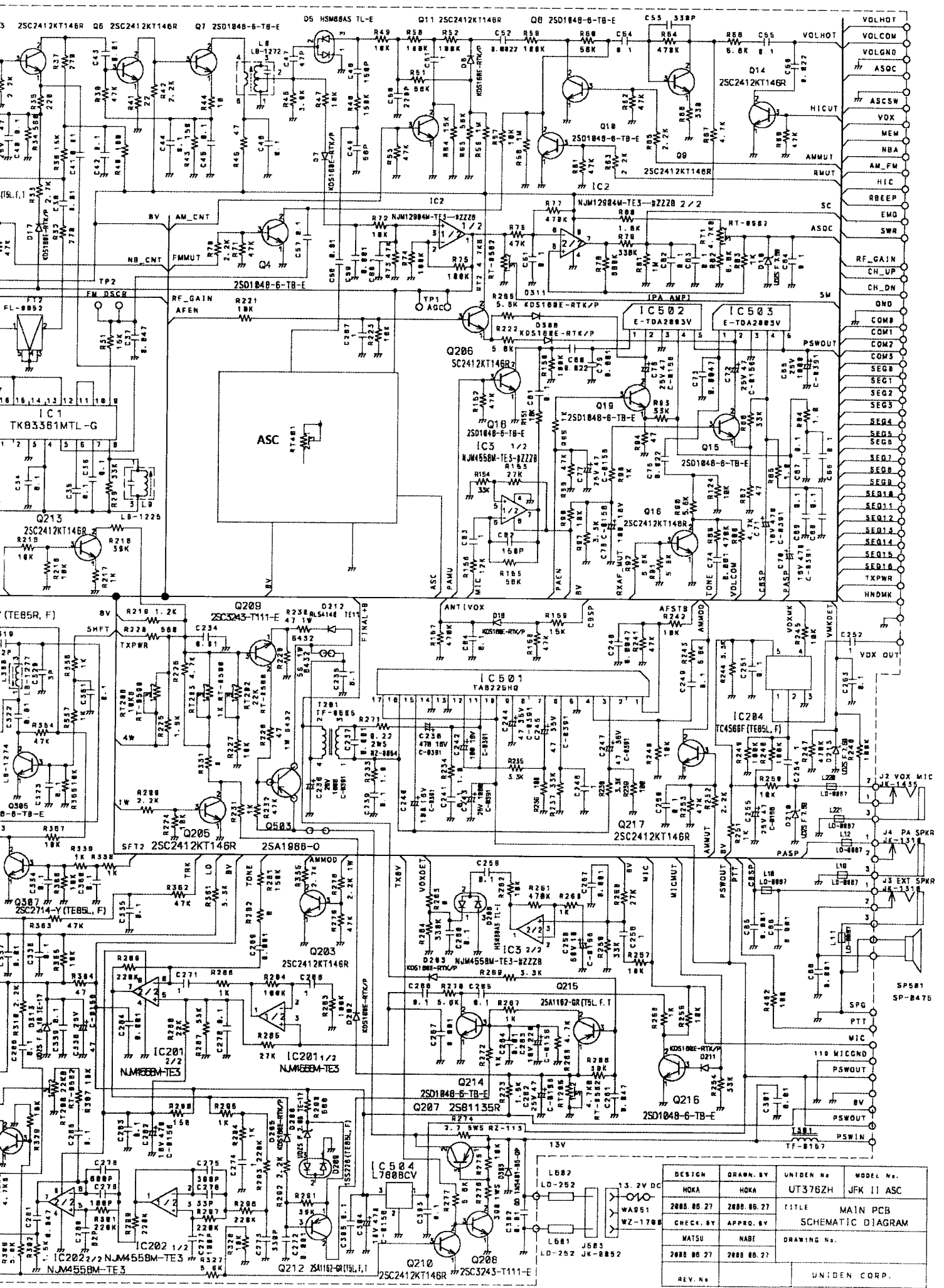
2SC2412KT146R

XC61B9C43ANR RH5RL58AA-T1-FA



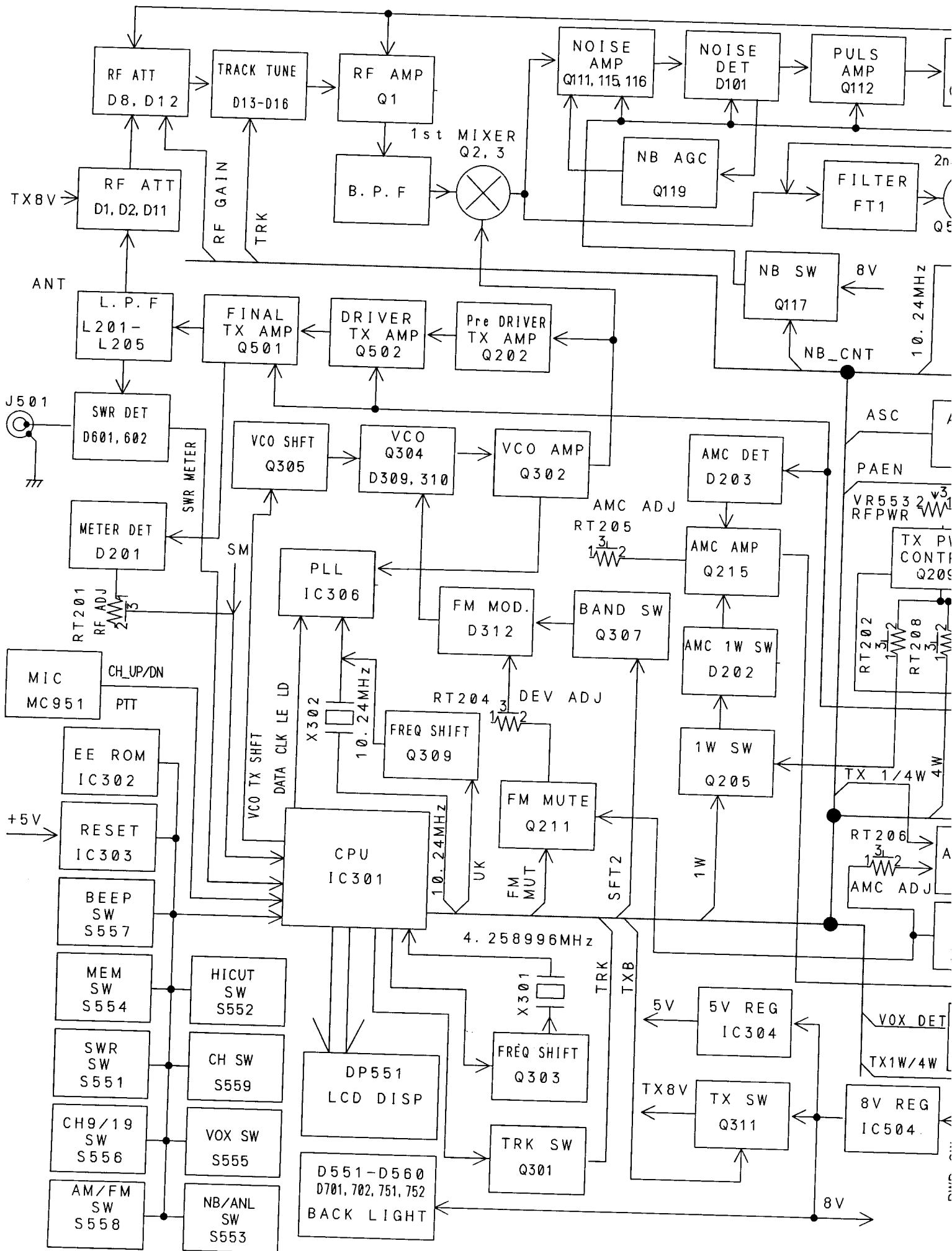
1c

1d



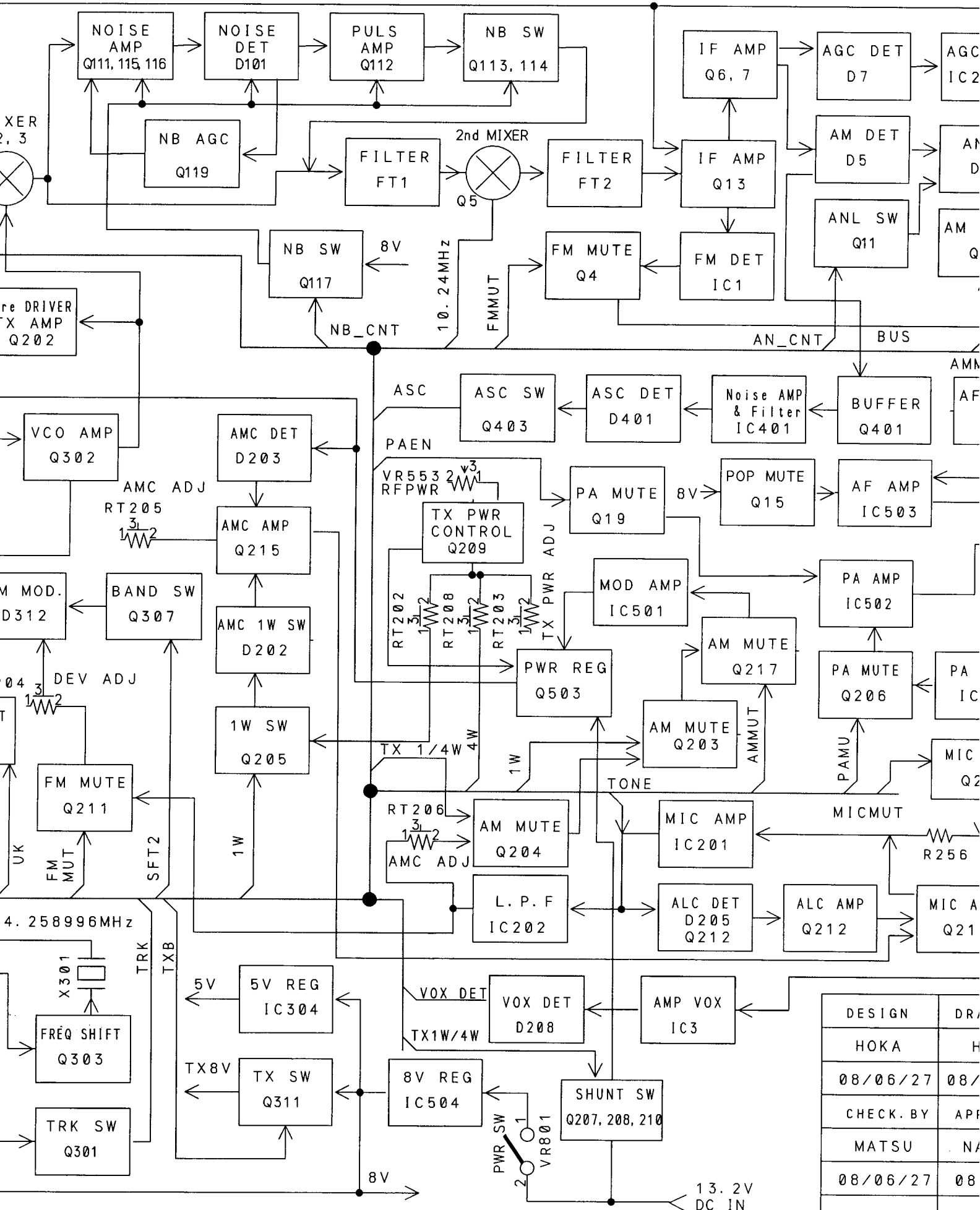
DESIGN	DRAWN BY	UNIDEN No	MODEL No.
HOKA	HOKA	UT376ZH	JFK II ASC
2008.06.27	2008.06.27	TITLE MAIN PCB	
WZ-170B	APPRO. BY	SCHEMATIC DIAGRAM	
2008.06.27	MATSU	DRAWING No.	
2008.06.27	NABE	UNIDEN CORP.	





2B

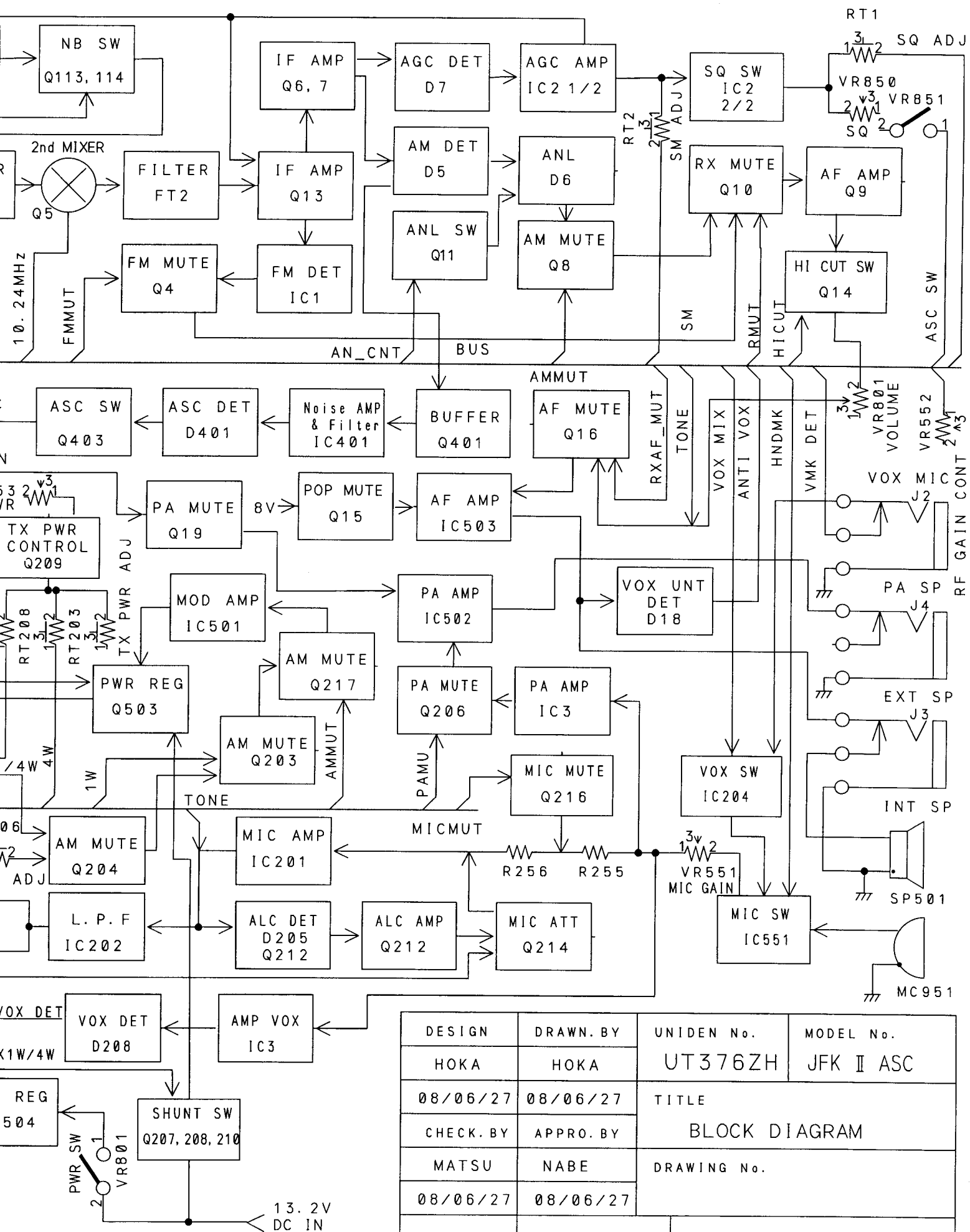
2C



DESIGN	DR
HOKA	H
08/06/27	08/
CHECK BY	APP
MATSU	NA
08/06/27	08
REV. No	

2C

2D



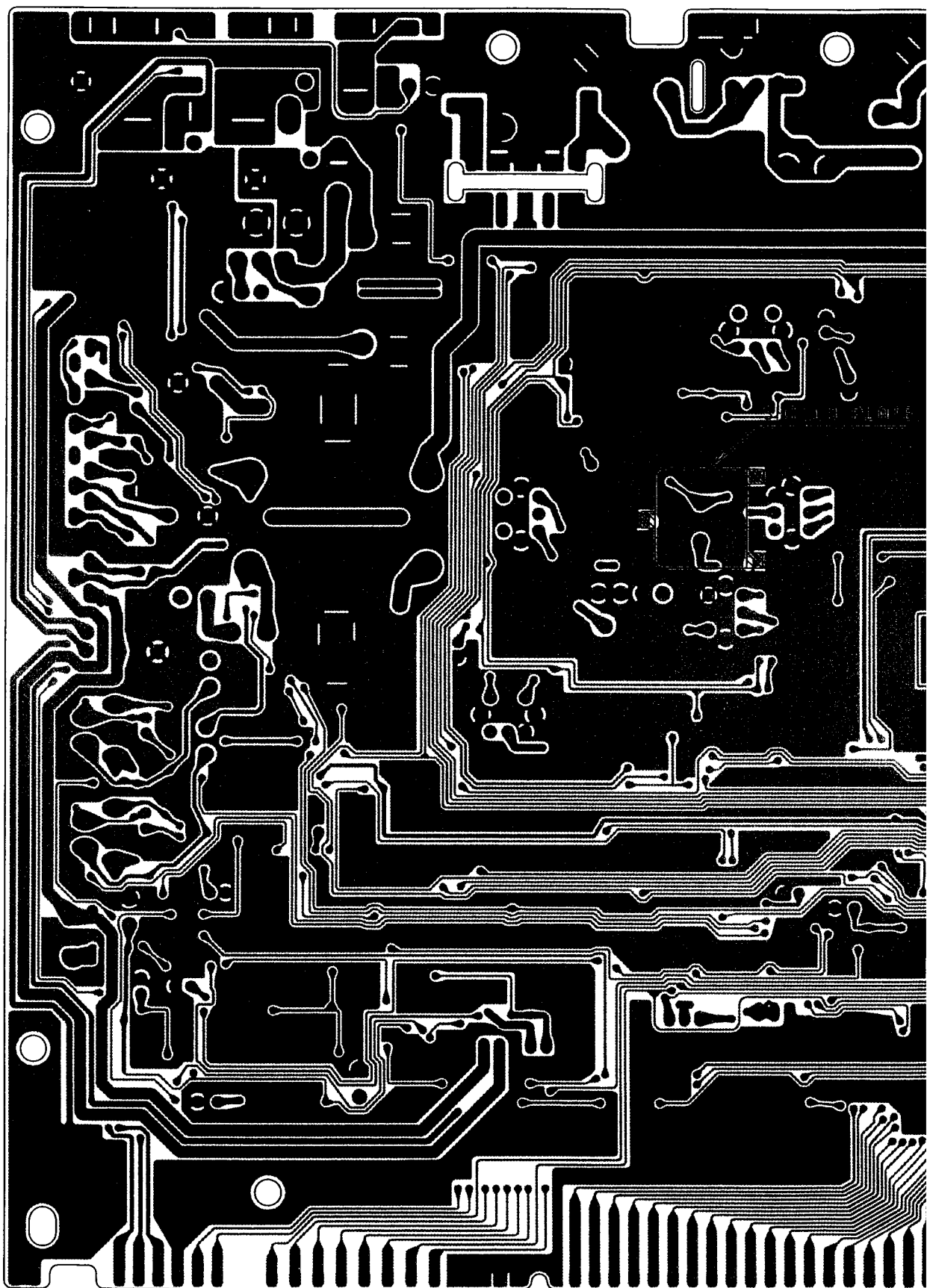
DESIGN	DRAWN. BY	UNIDEN No.	MODEL No.
HOKA	HOKA	UT376ZH	JFK II ASC
08/06/27	08/06/27	TITLE BLOCK DIAGRAM	
CHECK. BY	APPRO. BY		
MATSU	NABE	DRAWING No.	
08/06/27	08/06/27		
REV. No			UNIDEN CORP.

3A

3B

Use Pb F

B1 PA-442AA (BOTTOM VIEW)

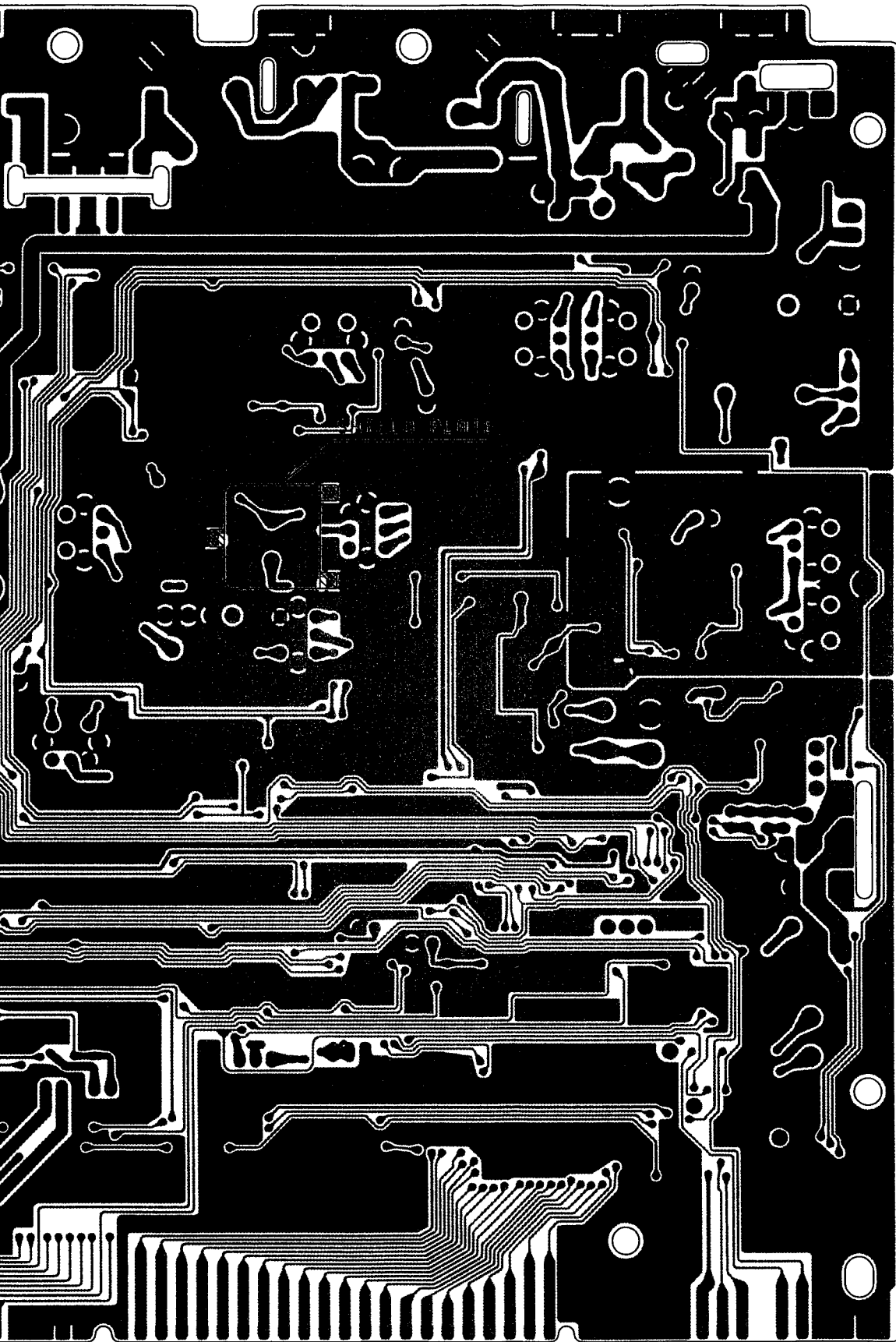


3B

3C

Use Pb Free Solder

IEW)

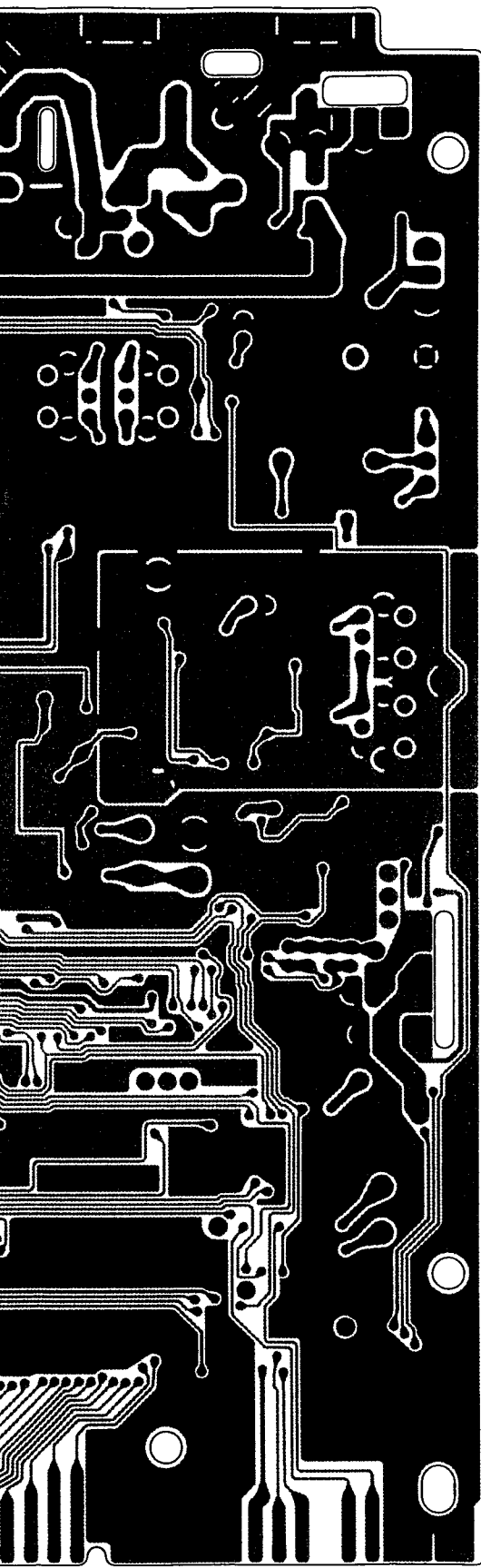


DES:	H
08/	
CHE	M
08/	F

3C

3D

Free Solder



DESIGN. BY	DRAWN. BY	JNIDEN NO.	MODEL NO.
HOKA	HOKA	UT376ZH	JFK II ASC
08/07/02	08/07/02	TITLE MAIN PCB	
CHECK. BY	APPRO. BY	PARTS ASS'Y BOTTOM VIEW	
MATSU	NABE	DRAWING NO.	
08/07/02	08/07/02		
REV. NO.		UNIDEN CORP.	

4A

4B


\* APPLY THERMAL COMPOUND (ZAYY0001001)

IC501, 502, 503, 504: REAR SIDE

Q501, 503: REAR SIDE

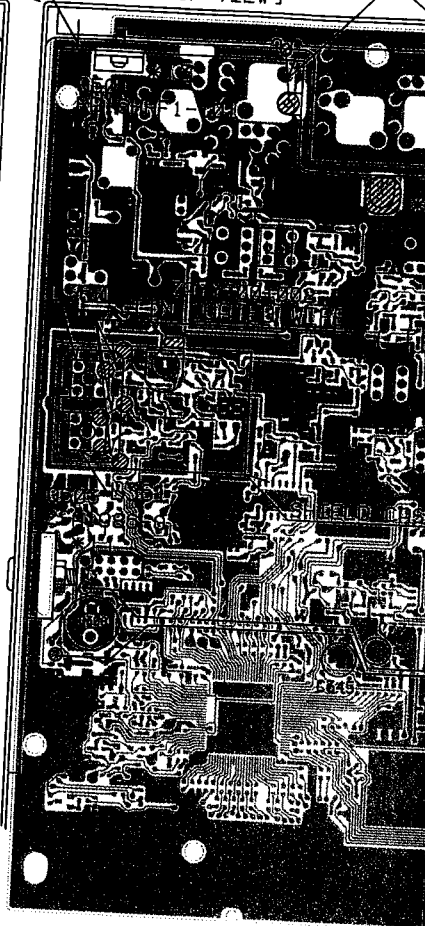
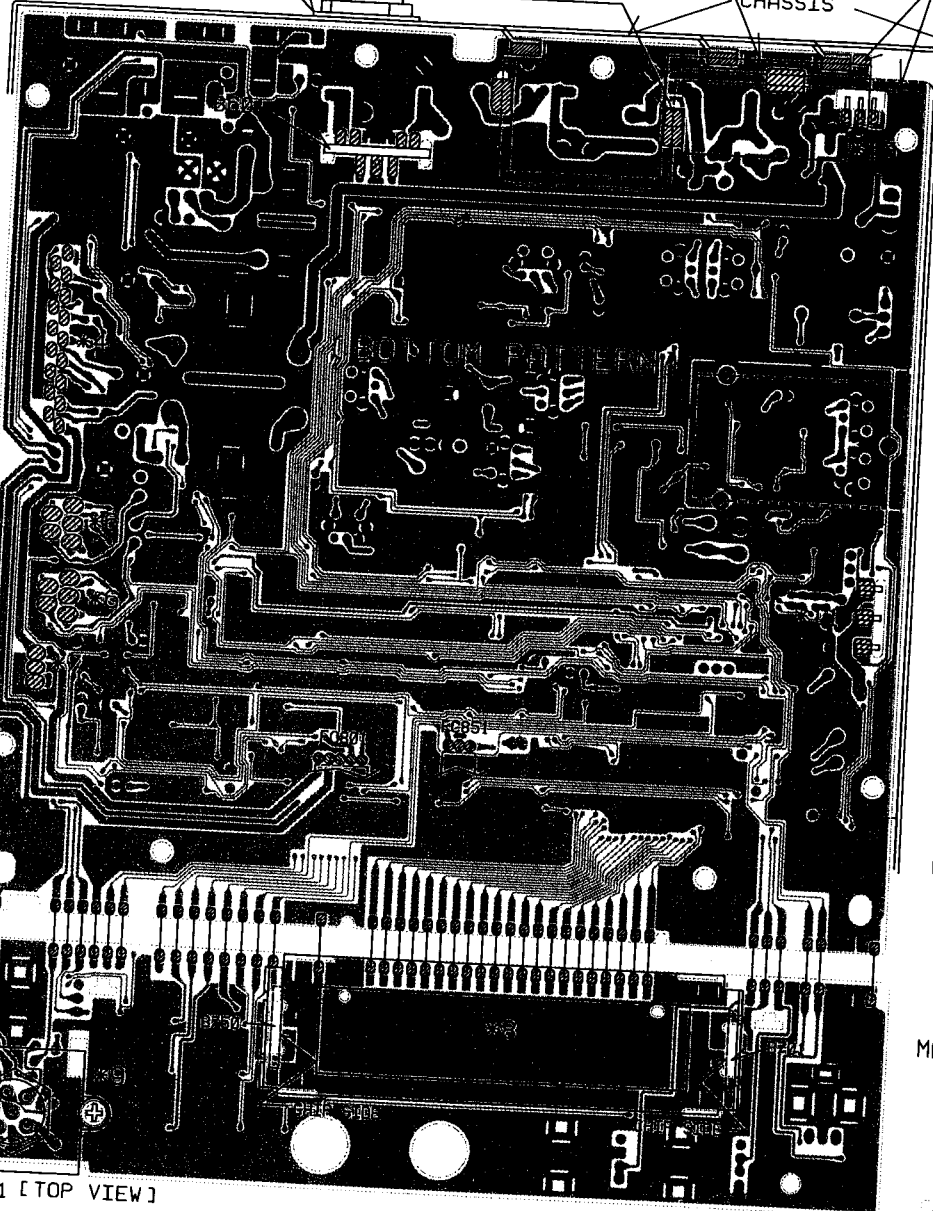
HEAT SINK & HEAT SINK(COMP): REAR SIDE(CHASSIS SIDE)

INSULATION PLATE: REAR SIDE(HEAT SINK SIDE)

 : SOLDERING

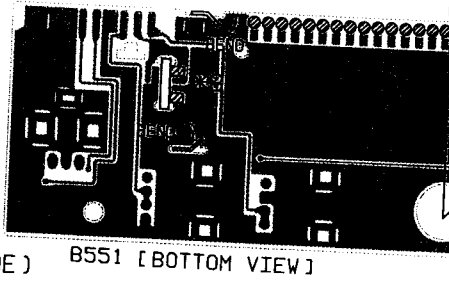
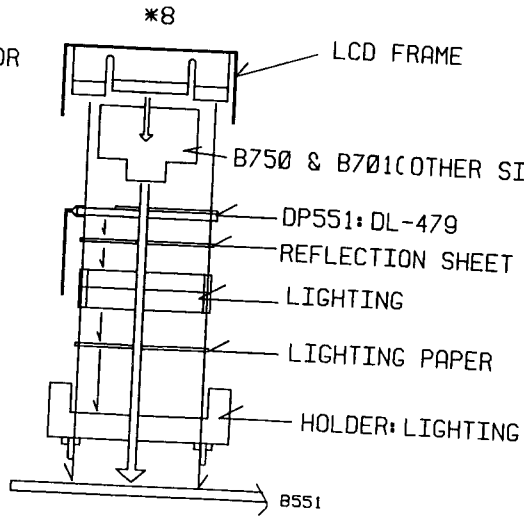
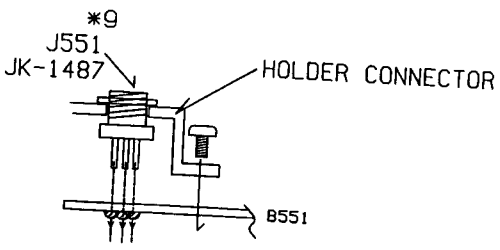
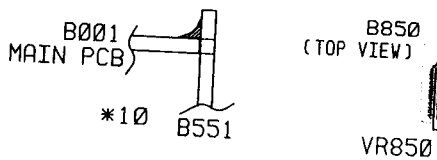
Use Pb free

HEXAGON NUT  
SPRING WASHER  
J501  
SHIELD PLATE  
HEAT SINK(COMP)  
SOLDERING  
CHASSIS  
TIN COATED WIRE  
ZAYY7001002  
B001 [TOP VIEW]



\*10  
J551

B551 [TOP VIEW]



4B

4C

OUND (ZAYY0001001)  
REAR SIDE  
REAR SIDE  
REAR SIDE(CHASSIS SIDE)  
REAR SIDE(HEAT SINK SIDE)

Use Pb free Solder

HEAT SINK(COMP)  
SOLDERING  
CHASSIS

TIN COATED WIRE  
ZAYY7001002  
B001 [TOP VIEW]

HOLDER: PCB

J501  
JK-1382

CUT &  
SOLDERING

J503  
JK-052

\*3

L501 & L502  
DO NOT TOUCH TO J3&J4

HEAT  
SINK

L502 & L501

B001  
MAIN PCB  
TOP SIDE SO

HEAT SINK \*4

HOLDER: IC

IC501  
TA8225HQ

\*4

W1 (GRY)

\*5  
SP501  
SP-475

W2 (WHT)

HOLDER: IC

\*6

IC502 & 503

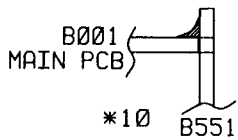
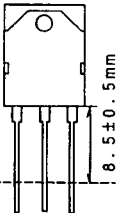
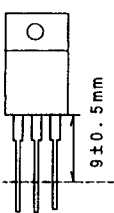
B001

SOLDERING

INSULAT

Q501

Q503



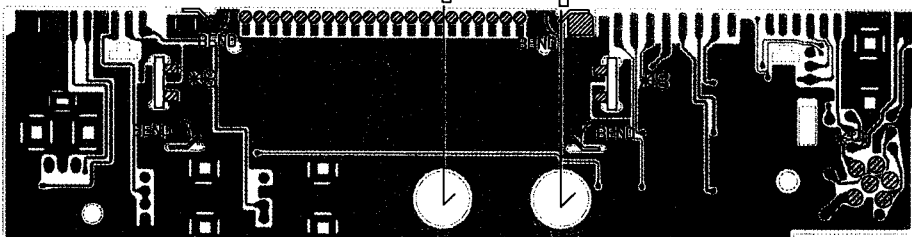
B850  
(TOP VIEW)

B801  
(TOP VIEW)

VR850

VR801

LCD FRAME



B701(OTHER SIDE)

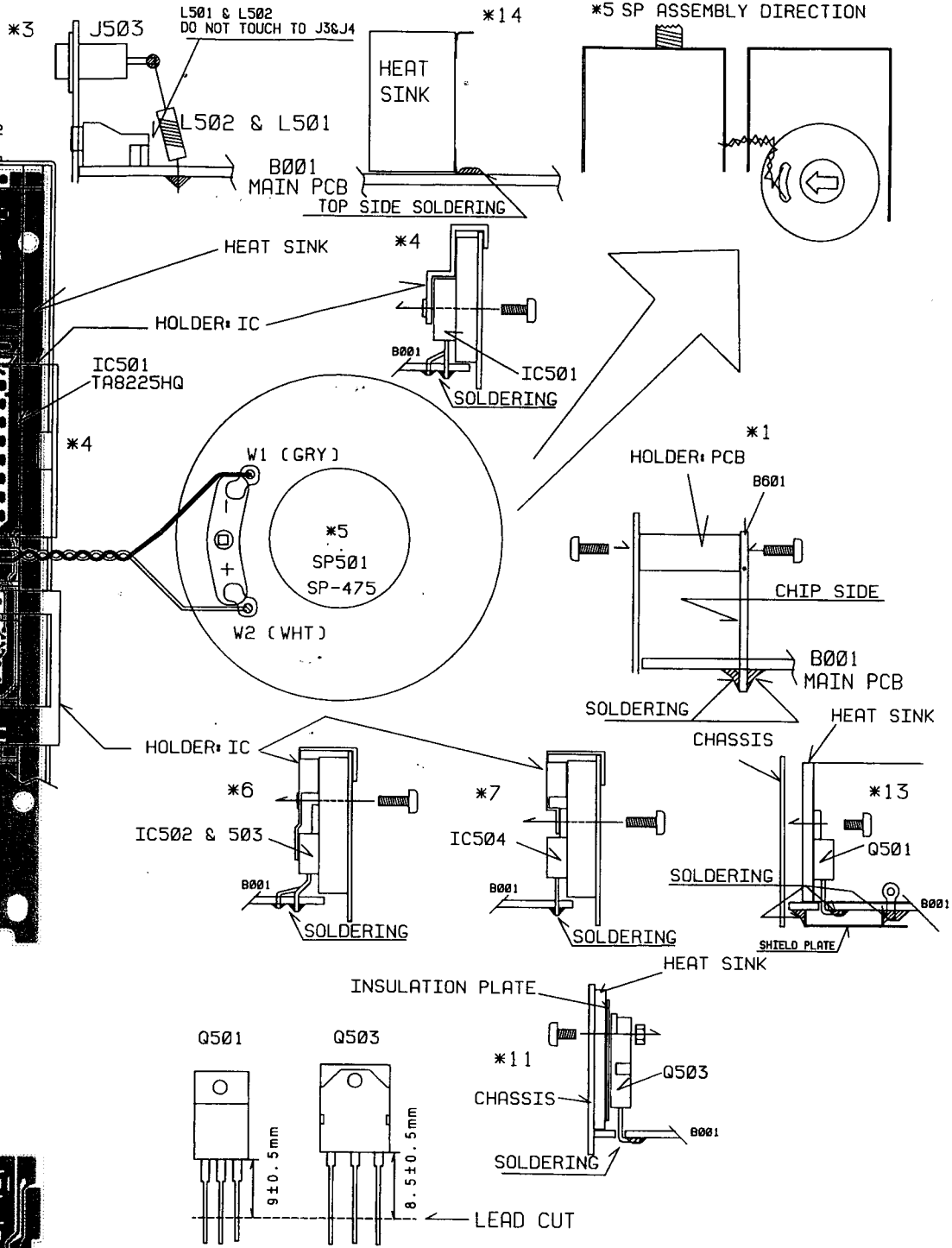
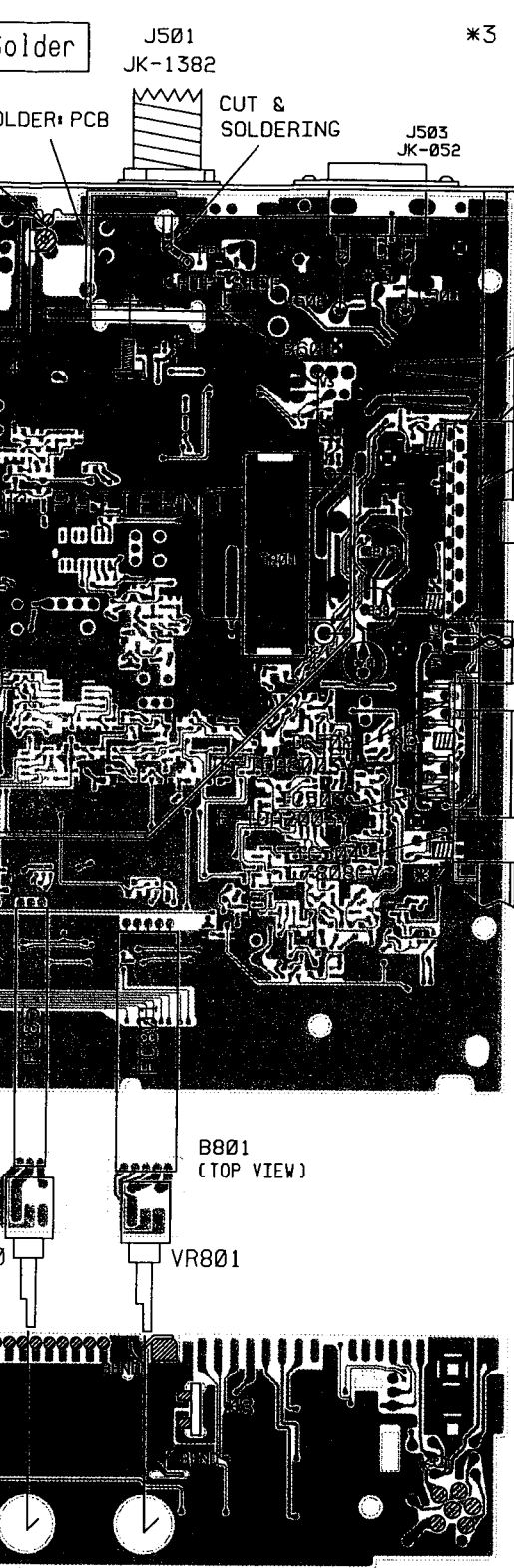
B551 [BOTTOM VIEW]

551: DL-479  
LECTION SHEET  
GHTING  
GHTING PAPER  
OLDER: LIGHTING



4C

4D



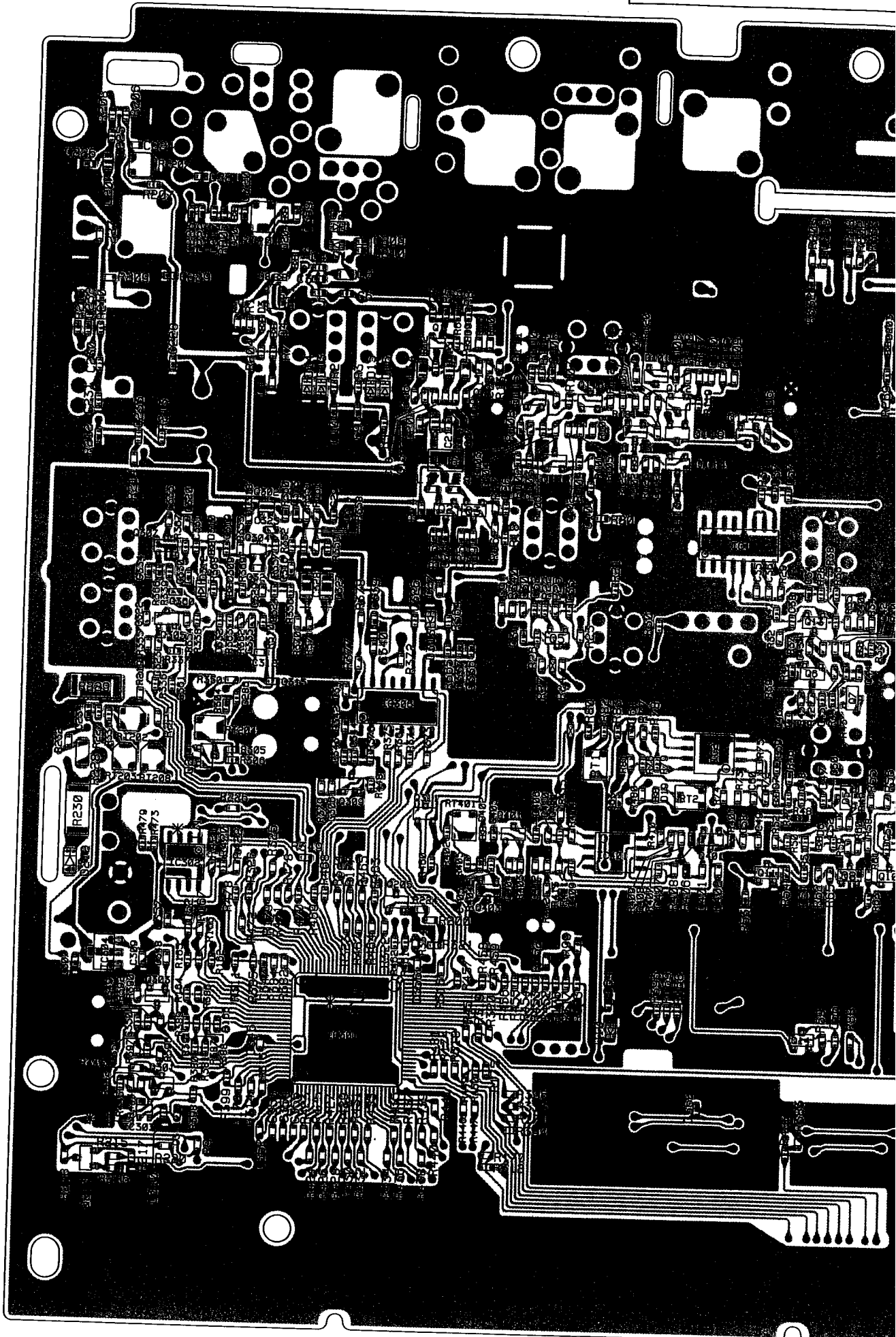
DESIGN. BY	DRAWN. BY	UNIDEN NO.	MODEL NO.
HOKA	HOKA	UT376ZH	JFK II ASC
08/07/02	08/07/02	TITLE	
CHECK. BY	APPRO. BY	WIRING DIAGRAM	
MATSU	NABE	DRAWING NO.	
08/07/02	08/07/02		
REV. NO.		UNIDEN CORP.	

5A

5B

B1 PA-442AA (TOP VIEW)

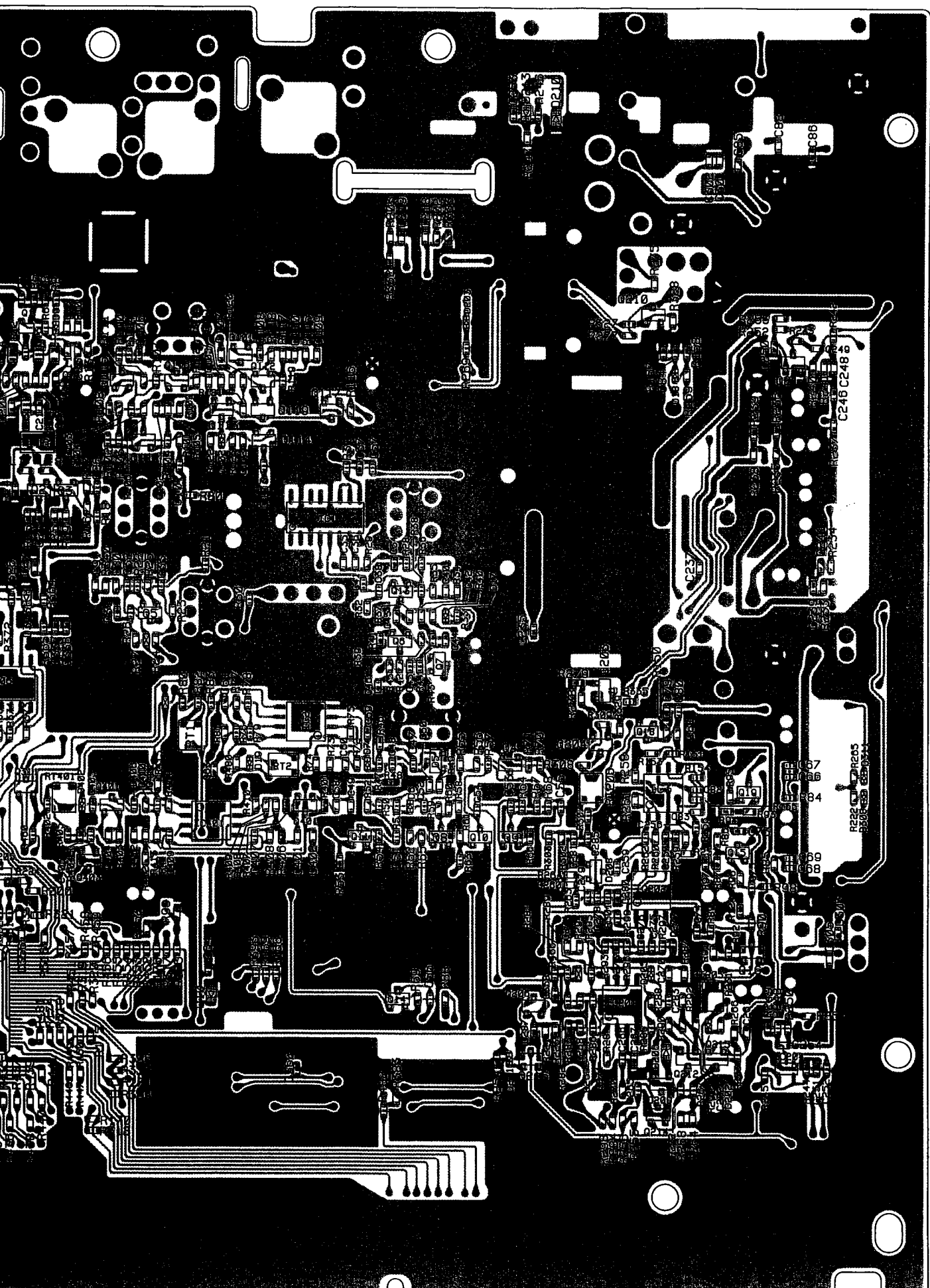
Use Pb



5B

5C

Use Pb Free Solder



\*1 IC3

\*2 INS  
PRO

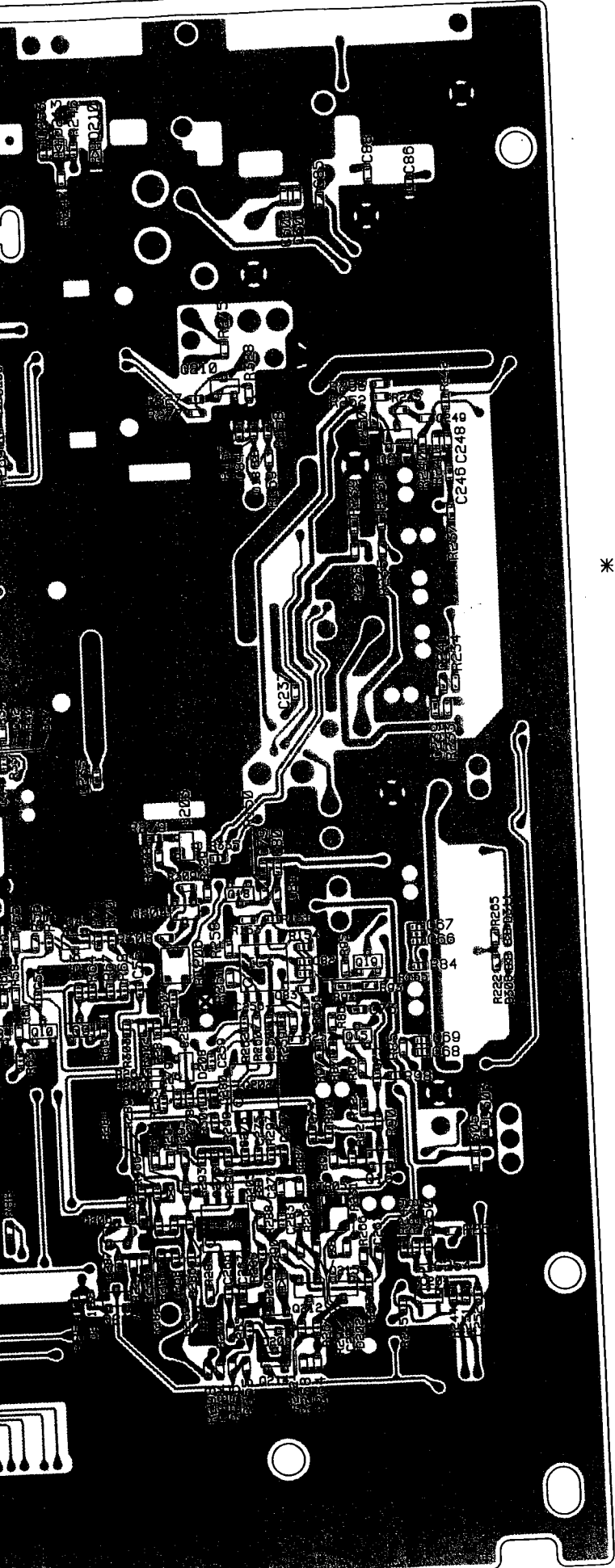
\*3 IC3  
1 P

DESIGN. BY	DR
HOKA	H
'88/07/02	'88
CHECK. BY	AF
WATSU	W
'88/07/02	'88
REV.	
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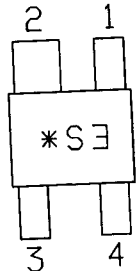
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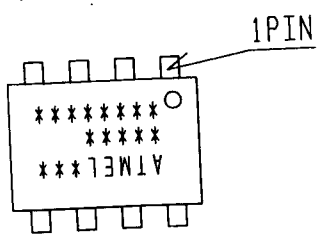


\*1 IC303 PIN POSITION



\*2 INSTALL IC301 AFTER PROGRAMMING

\*3 IC302 MARKING & 1 PIN POSITION



DESIGN. BY HOKA	DRAWN. BY HOKA	UNIDEN NO. UT376ZH	MODEL NO. JFK IASC
CHECK. BY NATSU	APPRO. BY NADE	TITLE MAIN ASS'Y CHIP LAYOUT TOP VIEW	
REV. NO.		DRAWING NO.	
		UNIDEN CORP.	